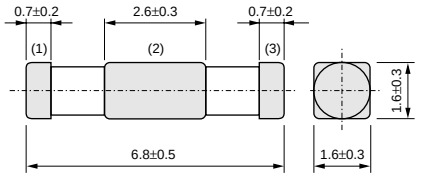
Chip EMIFIL® LC Combined Type T Type EMIFIL®

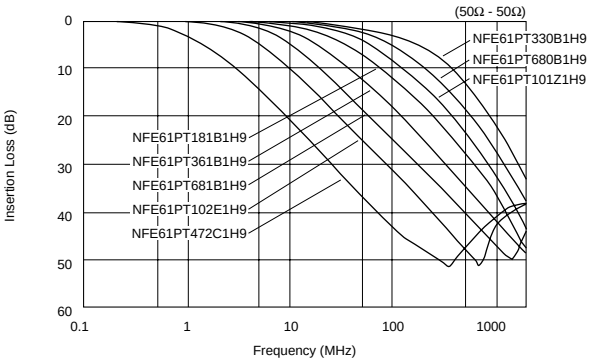
NFE61P Series (2606 Size) for Large Current

■ Dimension

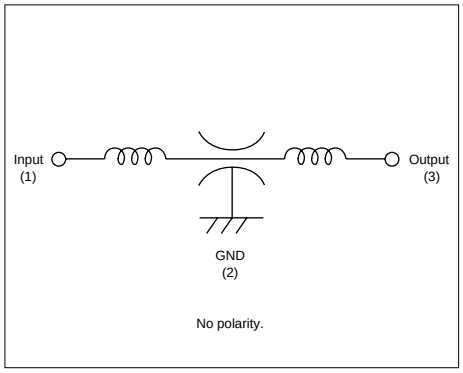


(in mm)

■ Insertion Loss Characteristics (Main)



■ Equivalent Circuit



■ Packaging

Code	Packaging	Minimum Quantity
L	180mm Embossed Tape	2500
K	330mm Embossed Tape	8000
B	Bulk(Bag)	500

■ Rated Value (☐: packaging code)

Part Number	Capacitance	Rated Current	Rated Voltage	Insulation Resistance (min.)	Operating Temperature Range
NFE61PT330B1H9☐	33pF+30%-30%	2A	50Vdc	1000M ohm	-25°C to +85°C
NFE61PT680B1H9☐	68pF+30%-30%	2A	50Vdc	1000M ohm	-25°C to +85°C
NFE61PT101Z1H9☐	100pF+30%-30%	2A	50Vdc	1000M ohm	-25°C to +85°C
NFE61PT181B1H9☐	180pF+30%-30%	2A	50Vdc	1000M ohm	-25°C to +85°C
NFE61PT361B1H9☐	360pF+20%-20%	2A	50Vdc	1000M ohm	-25°C to +85°C
NFE61PT681B1H9☐	680pF+30%-30%	2A	50Vdc	1000M ohm	-25°C to +85°C
NFE61PT102E1H9☐	1000pF+80%-20%	2A	50Vdc	1000M ohm	-25°C to +85°C
NFE61PT472C1H9☐	4700pF+80%-20%	2A	50Vdc	1000M ohm	-25°C to +85°C

Number of Circuit: 1

Continued on the following page.

● This data sheet is applied for CHIP EMIFIL® used for General Electronics equipment for your design.

⚠Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

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Continued from the preceding page.

■ ⚠Caution/Notice

⚠Caution (Rating)

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

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